# 2SB1079

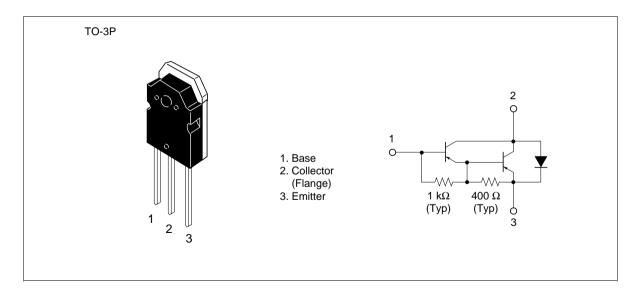
## Silicon PNP Triple Diffused

# **HITACHI**

#### **Application**

Low frequency power amplifier complementary pair with 2SD1559

#### Outline





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### **Absolute Maximum Ratings** $(Ta = 25^{\circ}C)$

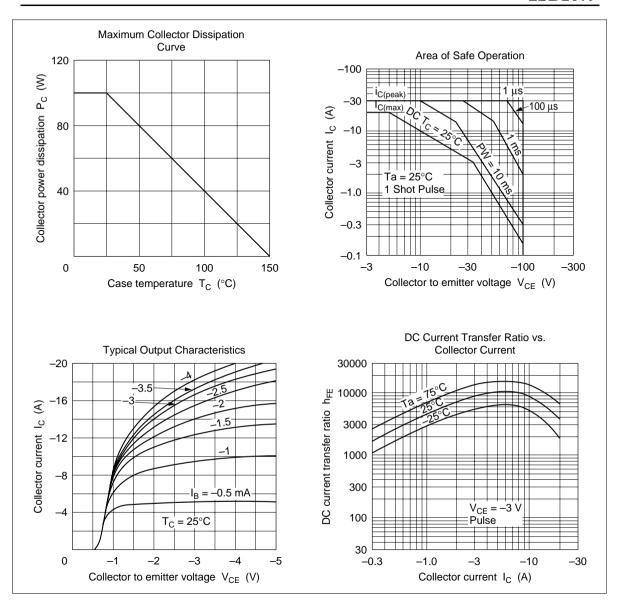
Item	Symbol	Ratings	Unit
Collector to base voltage	$V_{\text{CBO}}$	-100	V
Collector to emitter voltage	V <sub>CEO</sub>	-100	V
Emitter to base voltage	$V_{EBO}$	<b>-7</b>	V
Collector current	I <sub>c</sub>	-20	A
Collector peak current	I <sub>C(peak)</sub>	-30	A
Base current	I <sub>B</sub>	-3	A
Collector power dissipation	Pc*1	100	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. Value at  $T_c = 25^{\circ}C$ .

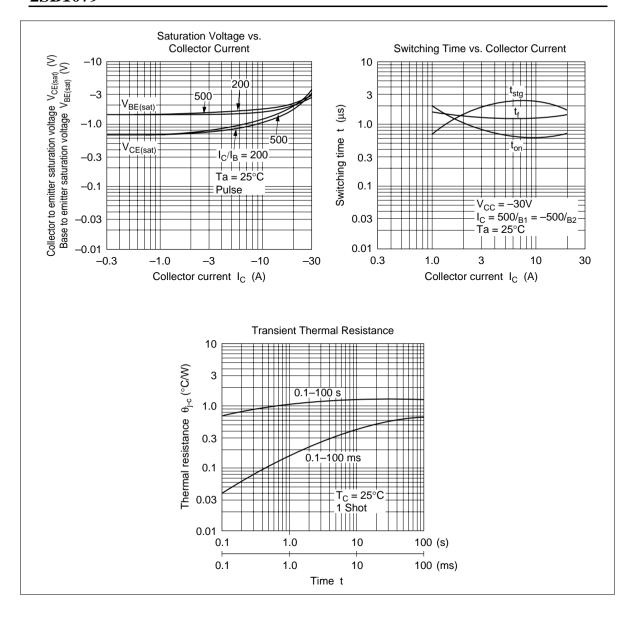
### **Electrical Characteristics** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-100	_	_	V	$I_{\rm C} = -0.1 \text{ mA}, I_{\rm E} = 0$
Collector to emitter breakdown voltage	$V_{(BRCEO}$	-100	_	_	V	$I_{\rm C} = -25$ mA, $R_{\rm BE} = \infty$
Collector to emitter sustain voltage	$V_{\text{CEO(sus)}}$	-100	_	_	V	$I_{\rm C} = -200 \text{ mA}, R_{\rm BE} = \infty^{*1}$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	<b>-7</b>	_	_	V	$I_{\rm E} = -50 \text{ mA}, I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	-100	μΑ	$V_{CB} = -100 \text{ V}, I_{E} = 0$
	I <sub>CEO</sub>	_	_	-1.0	mA	$V_{CE} = -80 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h <sub>FE</sub>	1000	_	20000		$V_{CE} = -3 \text{ V}, I_{C} = -10 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE}(\text{sat})1}$	_	_	-2.0	V	$I_{\rm C} = -10 \text{ A}, I_{\rm B} = -20 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)1}$	_	_	-2.5	V	_
Collector to emitter saturation voltage	V <sub>CE(sat)2</sub>	_	_	-3.0	V	$I_{\rm C} = -20 \text{ A}, I_{\rm B} = -200 \text{ mA}^{*1}$
Base to emitter saturation voltage	$V_{BE(sat)2}$	_	_	-3.5	V	_
Turn on time	t <sub>on</sub>	_	0.6	_	μs	$I_{\rm C} = -10 \text{ A}, I_{\rm B1} = -I_{\rm B2} = -20 \text{ mA}$
Storage time	t <sub>stg</sub>	_	3.5	_	μs	<del></del>

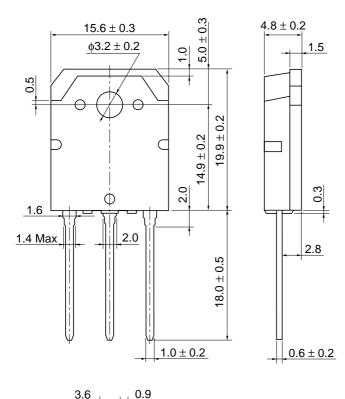
Note: 1. Pulse Test.

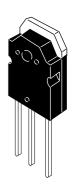


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Unit: mm





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5.45 ± 0	0.5					5.4	45 ±	0.5

Hitachi Code	TO-3P
JEDEC	
EIAJ	Conforms
Weight (reference value)	5.0 g

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